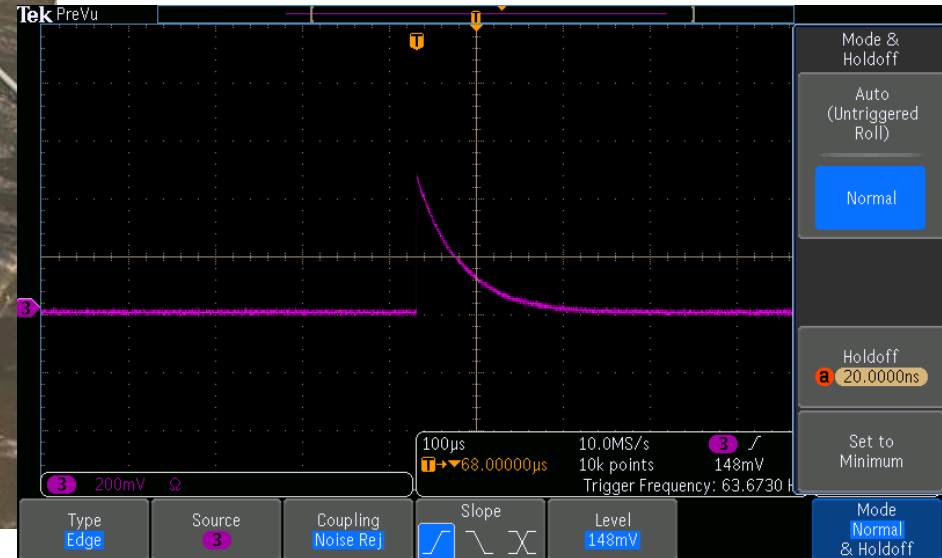
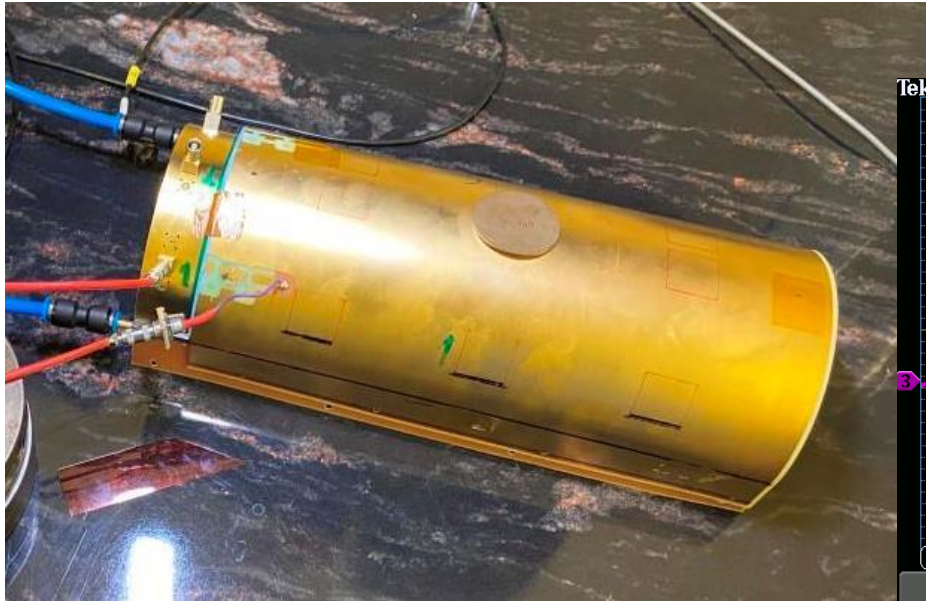


Status of MCT:

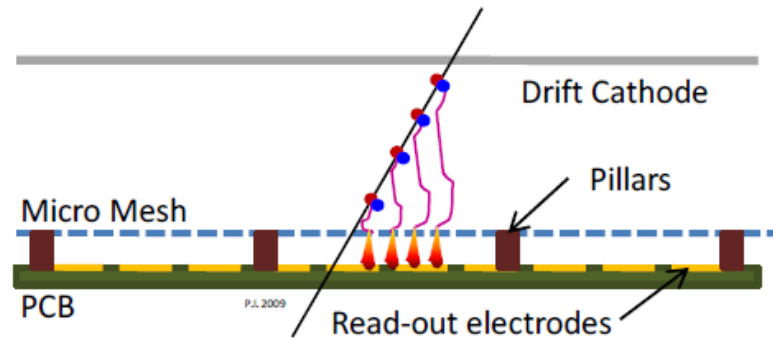
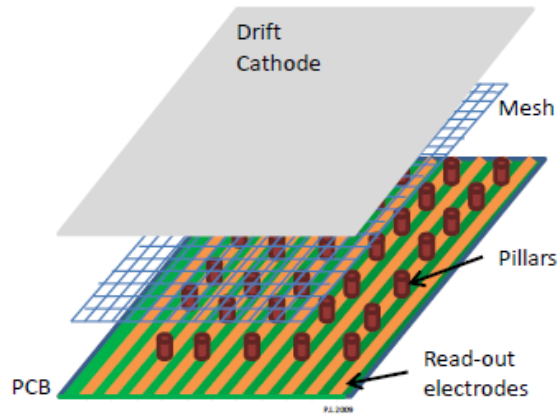
First cylindrical prototype

First cylindrical MM prototype is working!



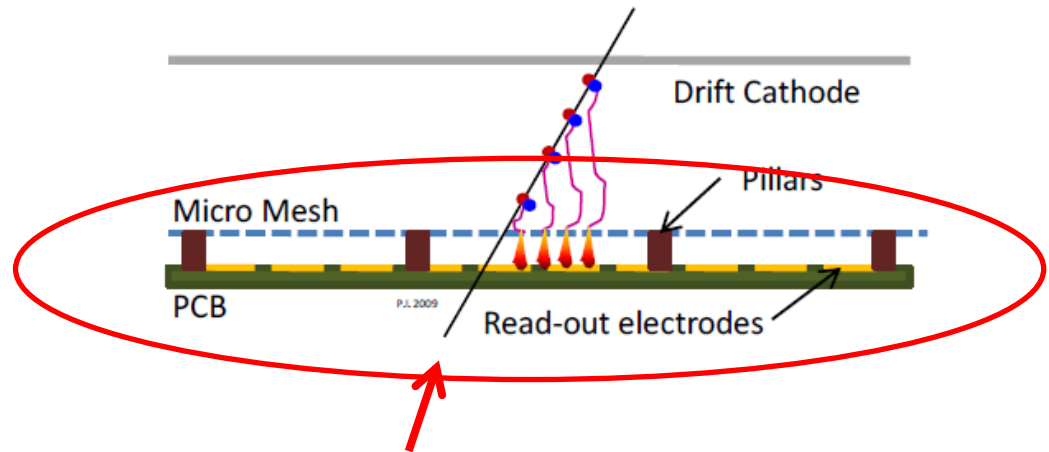
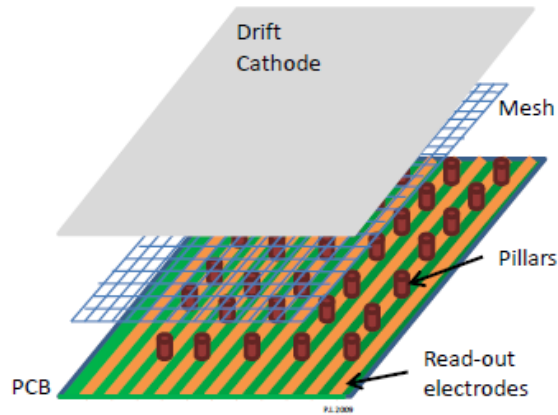
- The only bent MM chambers was produced by Saclay group for CLAS12 exp. , $R=40\text{cm}$
- MCT with $R=5\text{cm}$ should be build for SPD

Micromegas detector



- Parallel plate proportional counter with dedicated ionization and amplification gaps separated by fine mesh
- Precise value of amplification gap is defined by isolating pillars
- Photolithography is used to produce RO board+ mesh sandwich

Micromegas detector



single non-disassembling module

- Parallel plate proportional counter with dedicated ionization and amplification gaps separated by fine mesh
- Precise value of amplification gap is defined by isolating pillars
- Photolithography is used to produce RO board+ mesh sandwich

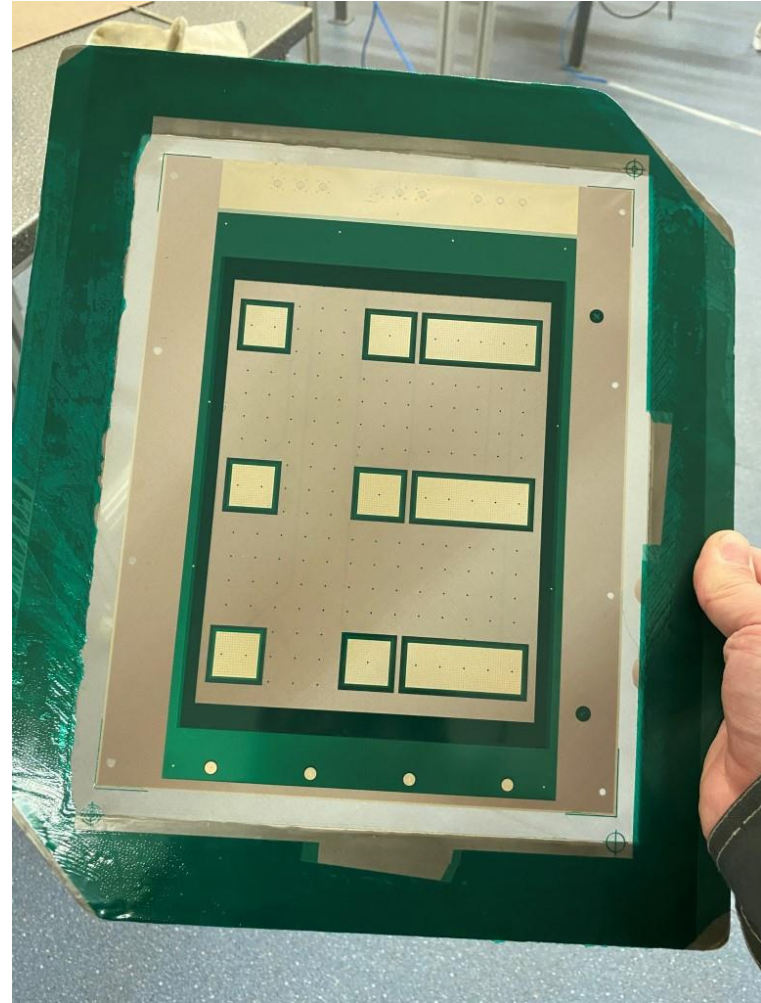
MM production-1



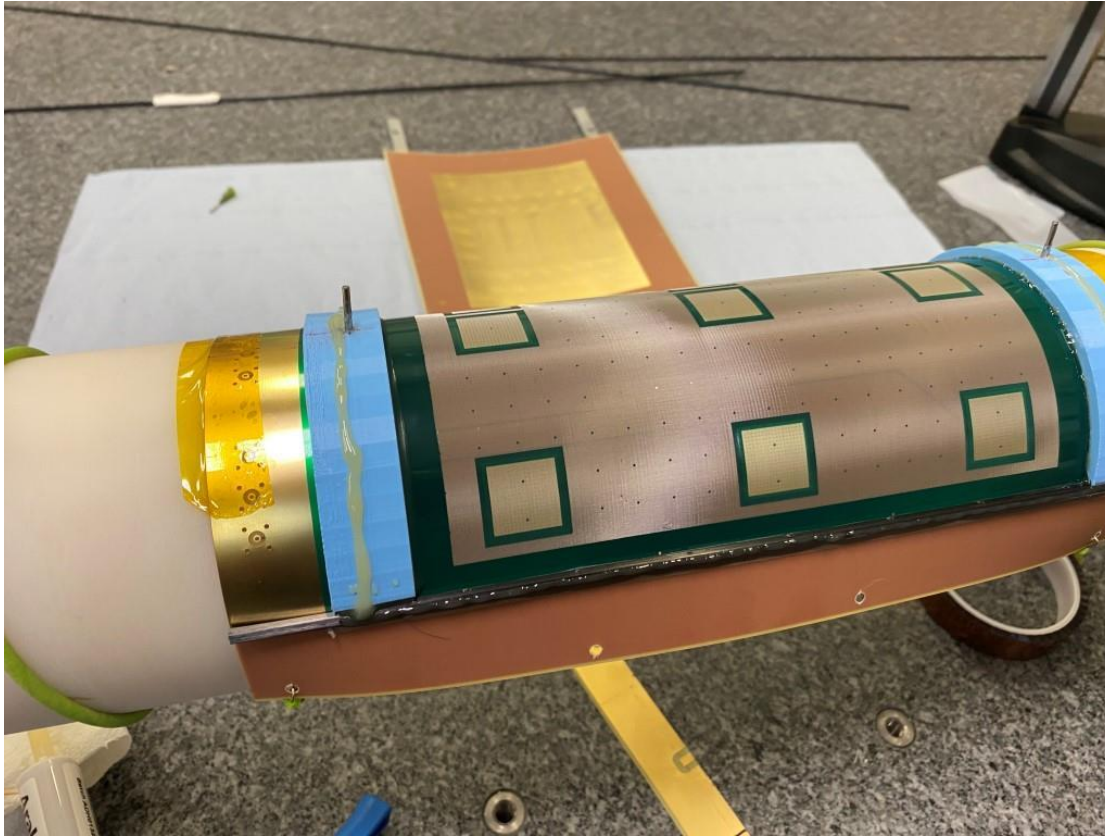
- Mesh pre-tension on temporary frame

MM production-2

- Photoresist applied on RO board, mesh fixed between photoresist layers
- exposition of photoresist to UV light through mask corresponding to desired pillar pattern etching of unexposed photoresist
- Main bulk MM module is ready for bending & assembling



MM production-3



- Bending & fixation on template
- Gluing force elements (longbeams, arcs)
- Gluing cathode plain & hermetization
- Finalization (cut-out technological detail, add gas connectors, etc)

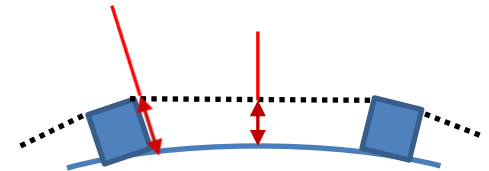
MM production-3



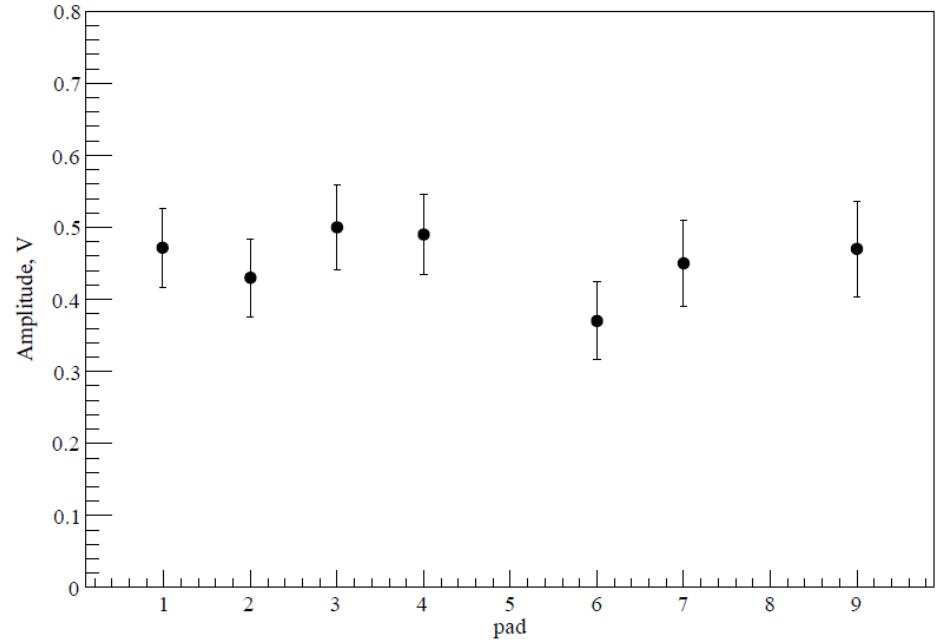
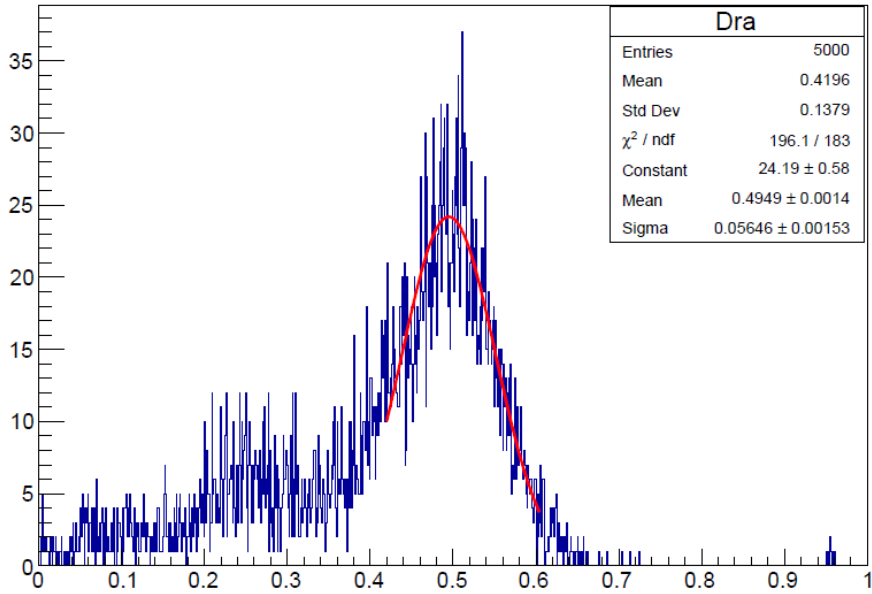
- Finalization (cut-out technological detail, add gas connectors, etc)

Why it's difficult to produce bent MM?

- Mesh tension increased due to bending: rough estimate gives $T \cong 50 \text{ N/cm}$, while typical value is $7 \div 10 \text{ N/cm}$
 - Change mesh orientation (~2 factor), optimize PCB structure (~1.5 factor)
- The stretched mesh has a flat shape between the pillars, due to which the distance from the mesh to the cylindrical surface of the anode varies significantly
 - Keep small pillar pitch



Gain uniformity



Next

- DLC degradation under discharge – **ongoing**
- Resolution test – 4 new MM chamber with 450 μ and 600 μ pitch - **assembling ongoing**
- Pillar pattern tests
- New, more realistic prototype